

# **FDD2670**

# 200V N-Channel PowerTrench® MOSFET

## **General Description**

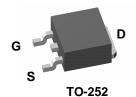
This N-Channel MOSFET has been de signed specifically to improve the overall efficiency of DC/DC converters u sing ei ther s ynchronous or conventional switching PWM controllers.

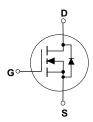
These M OSFETs f eature f aster s witching and lower gate c harge than ot her M OSFETs w ith comparable  $RDS_{(\text{ON})}$  specifications.

The result is a MOSFET that is easy and safer to drive (even at very hi gh f requencies), and DC/DC power supply designs with higher overall efficiency.

### **Features**

- 3.6 A, 200 V.  $R_{DS(ON)} = 130 \text{ m}\Omega$  @  $V_{GS} = 10 \text{ V}$
- Low gate charge
- Fas t switching speed
- High performance trench technology for extremely low  $R_{\text{DS(ON)}}$
- · High power and current handling capability





# Absolute Maximum Ratings T<sub>A</sub>=25°C unless otherwise noted

Symbol	Parameter	Ratings	Units	
V <sub>DSS</sub>	Drain-Source Voltage		200	V
$V_{GSS}$	Gate-Source Voltage		±20	V
I <sub>D</sub>	Drain Current - Continuous	(Note 1)	3.6	Α
	Drain Current - Pulsed		20	
P <sub>D</sub>	Maximum Power Dissipation @ T <sub>C</sub> = 25°C	(Note 1)	70	W
	@ T <sub>A</sub> = 25°C	(Note 1a)	3.2	
	@ T <sub>A</sub> = 25°C	(Note 1b)	1.3	
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	3.2	V/ns
$T_J$ , $T_{STG}$	Operating and Storage Junction Temperature Range		-55 to +150	°C

### **Thermal Characteristics**

$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	(Note 1)	1.8	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1b)	96	°C/W

# **Package Marking and Ordering Information**

Device Marking	Device	Reel Size	Tape width	Quantity
FDD2670 FDD2670		13"		

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Drain-Sc	ource Avalanche Ratings (Note	1)		.1	I	ı
W <sub>DSS</sub>	Single Pulse Drain-Source Avalanche Energy	$V_{DD} = 100 \text{ V},  I_D = 3.6 \text{ A}$			375	mJ
I <sub>AR</sub>	Maximum Drain-Source Avalanche Current				3.6	Α
Off Char	acteristics					
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA	200			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D$ = 250 $\mu$ A, Referenced to 25°C		214		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 160 V, V <sub>GS</sub> = 0 V			1	μΑ
I <sub>GSSF</sub>	Gate-Body Leakage, Forward	$V_{GS} = 20 \text{ V}, \qquad V_{DS} = 0 \text{ V}$			100	NA
I <sub>GSSR</sub>	Gate-Body Leakage, Reverse	$V_{GS} = -20 \text{ V},  V_{DS} = 0 \text{ V}$			-100	NA
On Char	acteristics (Note 2)	•		•		•
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2	4	4.5	V
$\Delta V_{GS(th)} \over \Delta T_{.1}$	Gate Threshold Voltage Temperature Coefficient	$I_D$ = 250 μA, Referenced to 25°C		-10		mV/°C
R <sub>DS(on)</sub>	Static Drain–Source On–Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 3.6 A V <sub>GS</sub> = 10 V, I <sub>D</sub> = 3.6 A T <sub>J</sub> = 125°C		100 205	130 275	mΩ
I <sub>D(on)</sub>	On-State Drain Current	V <sub>GS</sub> = 10 V, V <sub>DS</sub> = 5 V	20			Α
<b>g</b> FS	Forward Transconductance	$V_{DS} = 5 \text{ V}, \qquad I_{D} = 3.6 \text{ A}$		15		S
Dvnamio	: Characteristics					
C <sub>iss</sub>	Input Capacitance	$V_{DS} = 100 \text{ V},  V_{GS} = 0 \text{ V},$		1228		PF
Coss	Output Capacitance	f = 1.0 MHz		112		PF
C <sub>rss</sub>	Reverse Transfer Capacitance	1		17		pF
Switchin	g Characteristics (Note 2)	1			ı	ı
t <sub>d(on)</sub>	Turn–On Delay Time	V <sub>DD</sub> = 100 V, I <sub>D</sub> = 1 A,		13	23	ns
t <sub>r</sub>	Turn–On Rise Time	$V_{GS} = 10 \text{ V}, \qquad R_{GEN} = 6 \Omega$		8	16	ns
$t_{\text{d(off)}}$	Turn-Off Delay Time	1 , , , , , , , , , , , , , , , , , ,		30	48	ns
t <sub>f</sub>	Turn-Off Fall Time	1		25	40	ns
Qg	Total Gate Charge	$V_{DS} = 100 \text{ V},  I_{D} = 3.6 \text{ A},$		27	43	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>GS</sub> = 10 V		7		nC
$Q_{gd}$	Gate-Drain Charge	1		10		nC
Drain-Se	ource Diode Characteristics a	and Maximum Ratings			•	•
l <sub>s</sub>	Maximum Continuous Drain–Source				2.1	Α
V <sub>SD</sub>	Drain–Source Diode Forward Voltage	$V_{GS} = 0 \text{ V},  I_S = 2.1 \text{ A}  \text{(Note 2)}$		0.7	1.2	V

### Notes

1.  $R_{\theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{\theta JC}$  is guaranteed by design while  $R_{\theta CA}$  is determined by the user's board design.

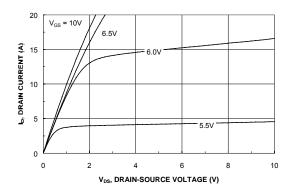


Scale 1 : 1 on letter size paper

**2.** Pulse Test: Pulse Width < 300 $\mu$ s, Duty Cycle < 2.0%

3.  $I_{SD} \leq 3A$ , di/dt  $\leq 100A/\mu s$ ,  $V_{DD} \leq BV_{DSS}$ , Starting  $T_J$  = 25°C

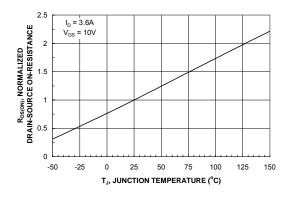
# **Typical Characteristics**



1.6 NORMALIZED ORAIN SOURCE ON RESISTANCE OF SOURCE ON SOURCE OF SOURC

Figure 1. On-Region Characteristics.

Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.



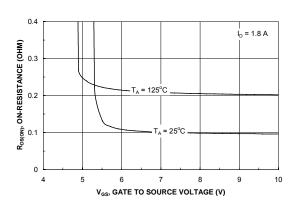
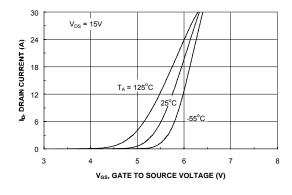


Figure 3. On-Resistance Variation with Temperature.

Figure 4. On-Resistance Variation with Gate-to-Source Voltage.



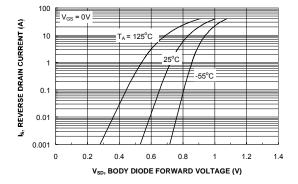
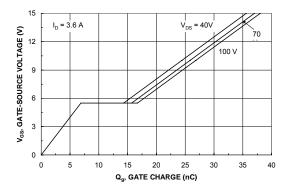


Figure 5. Transfer Characteristics.

Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

# **Typical Characteristics**



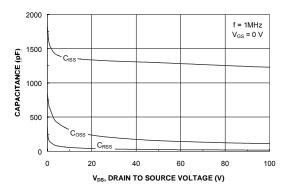


Figure 7. Gate Charge Characteristics.

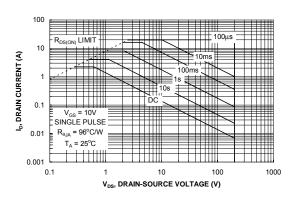


Figure 8. Capacitance Characteristics.

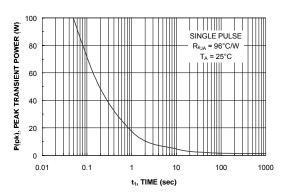


Figure 9. Maximum Safe Operating Area.



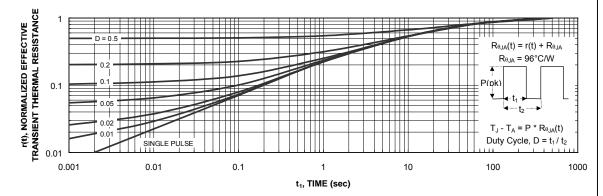
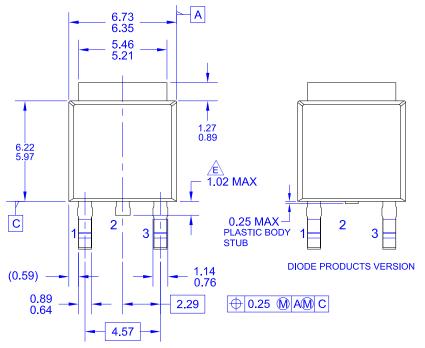
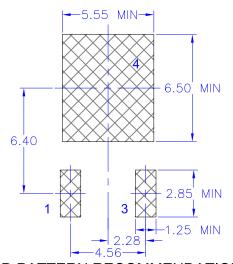


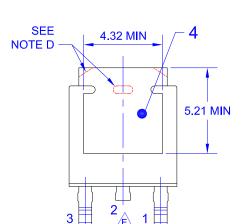
Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1b. Transient thermal response will change depending on the circuit board design.



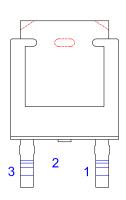


LAND PATTERN RECOMMENDATION

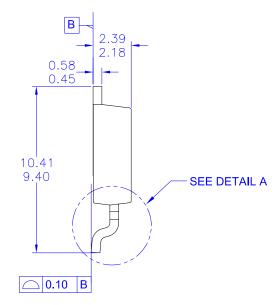


NON-DIODE PRODUCTS VERSION





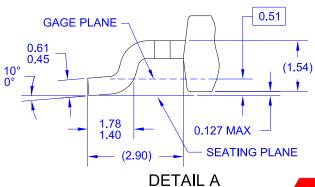
DIODE PRODUCTS VERSION



### NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE CONFORMS TO JEDEC, TO-252,
- ISSUE C, VARIATION AA.

  B) ALL DIMENSIONS ARE IN MILLIMETERS.
  C) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009.
- D) SUPPLIER DEPENDENT MOLD LOCKING HOLES OR CHAMFERED CORNERS OR EDGE PROTRUSION.
- E) TRIMMED CENTER LEAD IS PRESENT ONLY FOR DIODE PRODUCTS F) DIMENSIONS ARE EXCLUSSIVE OF BURSS,
  - MOLD FLASH AND TIE BAR EXTRUSIONS.
- G) LAND PATTERN RECOMENDATION IS BASED ON IPC7351A STD TO228P991X239-3N.
- H) DRAWING NUMBER AND REVISION: MKT-TO252A03REV10



(ROTATED -90°) SCALE: 12X







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Rev. 174

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